# JV- RMP4 Stencils - Datasheet

## Product Overview:

Whenever a BGA component is removed from an assembly, the attachment balls must be replaced before it can be reused. It's frustrating and very costly to throw away good components that could be recovered with the right tools.

The unavailability of the new BGA components as replacement for damaged ones makes re-balling is the only alternative.

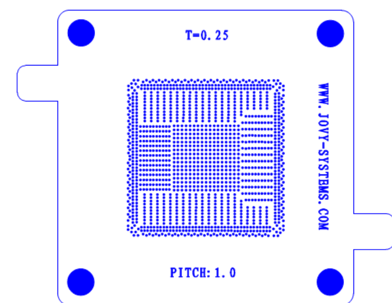
JV-RMP4 is a package of PS4 most reworkable BGAs. Package contains 4 stencils for the following BGAs
- SCEI (Sony Computer Entertainment, Inc.) CXD90026G SoC
- SCEI CXD90025G Secondary/Low Power Processor for Network Tasks
- Samsung K4B2G1646E-BCK0/2Gb DDR3 SDRAM
- Samsung K4G41325FC-HC03/ 4 Gb (512 MB) GDDR5 RAM

## Technical specifications

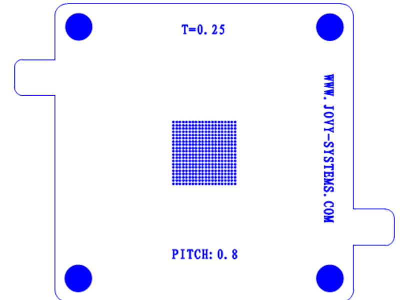
| | |
|---|---|
| Technology used to make the stencils | Laser cut |
| Material used | Stainless Steel |
| Stencil thickness | *0.30mm and 0.25mm (300 micron and 250 micron)* |
| Aperture tolerance | *6.35 micron* |

## Product details

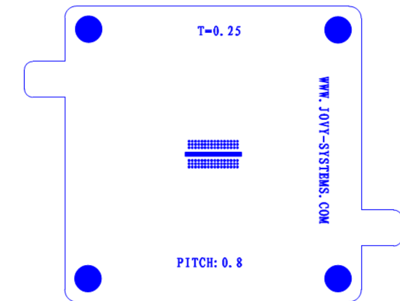
1- SCEI CXD90026G SoC package
Ball Size 0.55mm



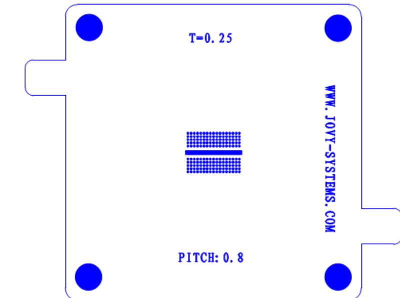
2- SCEI CXD90025G Secondary/Low Power Processor for Network Tasks
Ball Size: 0.40mm




3- Samsung K4B2G1646E-BCK0/2Gb DDR3 SDRAM
Ball Size: 0.40mm




4- Samsung K4G41325FC-HC03/ 4 Gb (512 MB) GDDR5 RAM
Ball Size: 0.40mm




## About

*Jovy Systems continues improve and develop the product lines according to the latest technology and operator's requirements.*

*In case this document is seeking any further information needed, contact support@jovy-sys.com*